

Silicon microstrip update

- schedule
 - in March
 - prototype sensor (version 1) production, 4 wafers (8 chips), completion in May
 - April
 - purchase of 250micron-thick wafers for mass production, 150 delivered immediately, 150-200 delivered in a few month → oxidization
 - VA2 chips delivered to BNL
 - telescope design, process & packaging (wire bonding etc.), 6 boards, completion in June
 - before July
 - DAQ for the telescope ready (VME, modules, PC, etc.)
 - July
 - test bench ready, laser (red or IR) + microscope + X-Y table, at BNL or at Wako
 - after July
 - beam test
 - final readout chip test
 - prototype sensor (version 2) ?
 - in next JFY (- March, 2003)
 - final sensor mass production start, 150 wafers
 - final readout mass production start
- other issues
 - mechanical frame
 - interface with PHENIX DAQ

